

BLF182XR; BLF182XRS

Power LDMOS transistor

Rev. 1 — 23 July 2015

Objective data sheet

1. Product profile

1.1 General description

A 250 W extremely rugged LDMOS power transistor for broadcast and industrial applications in the HF to 600 MHz band.

Table 1. Application information

Test signal	f (MHz)	V _{DS} (V)	P _L (W)	G _p (dB)	η _D (%)
pulsed RF	108	50	250	28	72

1.2 Features and benefits

- Easy power control
- Integrated ESD protection
- Excellent ruggedness
- High efficiency
- Excellent thermal stability
- Designed for broadband operation (HF to 600 MHz)
- Compliant to Directive 2002/95/EC, regarding Restriction of Hazardous Substances (RoHS)

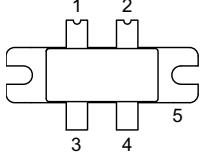
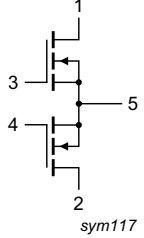
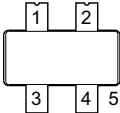
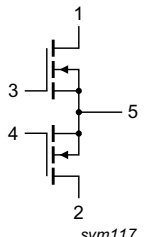
1.3 Applications

- Industrial, scientific and medical applications
- Broadcast transmitter applications



2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
BLF182XR (SOT1121A)			
1	drain1		 <p style="text-align: right;">sym117</p>
2	drain2		
3	gate1		
4	gate2		
5	source [1]		
BLF182XRS (SOT1121B)			
1	drain1		 <p style="text-align: right;">sym117</p>
2	drain2		
3	gate1		
4	gate2		
5	source [1]		

[1] Connected to flange.

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BLF182XR	-	flanged LDMOST ceramic package; 2 mounting holes; 4 leads	SOT1121A
BLF182XRS	-	earless flanged ceramic package; 4 leads	SOT1121B

4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage		-	135	V
V_{GS}	gate-source voltage		-6	+11	V
T_{stg}	storage temperature		-65	+150	°C
T_j	junction temperature	[1]	-	225	°C

[1] Continuous use at maximum temperature will affect the reliability, for details refer to the on-line MTF calculator.

5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-c)}$	thermal resistance from junction to case	$T_j = 115\text{ °C}$ [1][2]	<tdb>	K/W
$Z_{th(j-c)}$	transient thermal impedance from junction to case	$T_j = 150\text{ °C}$; $t_p = 100\text{ }\mu\text{s}$; $\delta = 20\%$ [3]	<tdb>	K/W

[1] T_j is the junction temperature.

[2] $R_{th(j-c)}$ is measured under RF conditions.

[3] See <tdb>.

6. Characteristics

Table 6. DC characteristics

$T_j = 25\text{ °C}$; per section unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{(BR)DSS}$	drain-source breakdown voltage	$V_{GS} = 0\text{ V}$; $I_D = 1.0\text{ mA}$	135	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$V_{DS} = 10\text{ V}$; $I_D = 100\text{ mA}$	1.25	1.8	2.25	V
V_{GSq}	gate-source quiescent voltage	$V_{DS} = 50\text{ V}$; $I_D = 50\text{ mA}$	-	1.6	-	V
I_{DSS}	drain leakage current	$V_{GS} = 0\text{ V}$; $V_{DS} = 50\text{ V}$	-	-	1.4	μA
I_{DSX}	drain cut-off current	$V_{GS} = V_{GS(th)} + 3.75\text{ V}$; $V_{DS} = 10\text{ V}$	-	14.3	-	A
I_{GSS}	gate leakage current	$V_{GS} = 11\text{ V}$; $V_{DS} = 0\text{ V}$	-	-	140	nA
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = V_{GS(th)} + 3.75\text{ V}$; $I_D = 3.5\text{ A}$	-	0.43	-	Ω

Table 7. AC characteristics

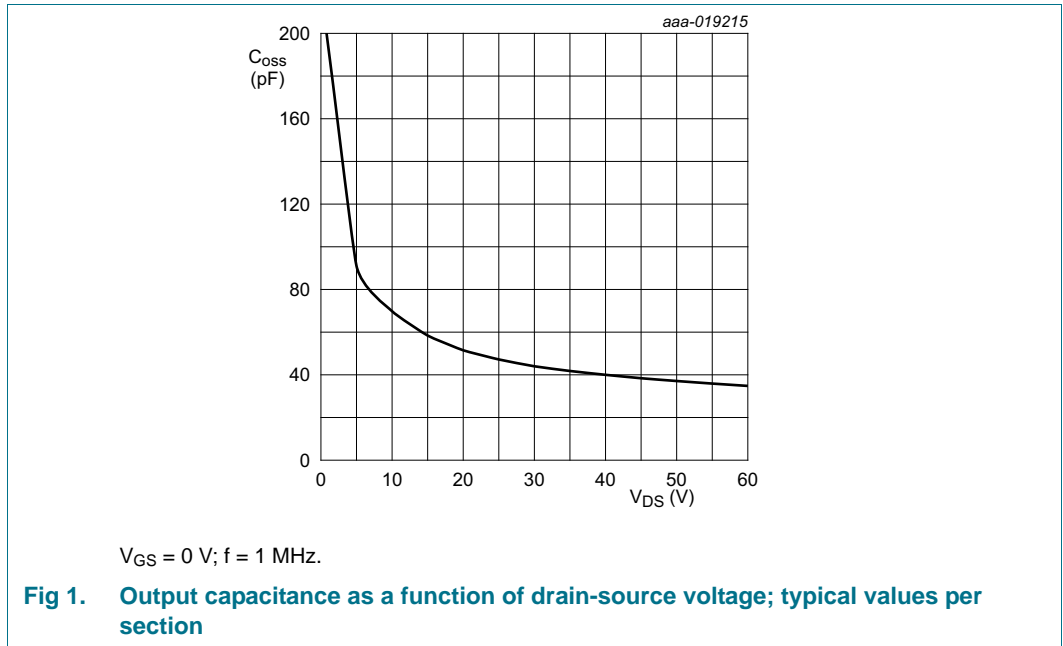
$T_j = 25\text{ °C}$; per section unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
C_{rs}	feedback capacitance	$V_{GS} = 0\text{ V}$; $V_{DS} = 50\text{ V}$; $f = 1\text{ MHz}$	-	0.7	-	pF
C_{iss}	input capacitance	$V_{GS} = 0\text{ V}$; $V_{DS} = 50\text{ V}$; $f = 1\text{ MHz}$	-	116	-	pF
C_{oss}	output capacitance	$V_{GS} = 0\text{ V}$; $V_{DS} = 50\text{ V}$; $f = 1\text{ MHz}$	-	37	-	pF

Table 8. RF characteristics

Test signal: pulsed RF; $t_p = 100\text{ }\mu\text{s}$; $\delta = 20\%$; $f = 108\text{ MHz}$; RF performance at $V_{DS} = 50\text{ V}$; $I_{Dq} = 100\text{ mA}$; $T_{case} = 25\text{ °C}$; unless otherwise specified; in a class-AB production test circuit.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
G_p	power gain	$P_L = 250\text{ W}$	<tdb>	28	-	dB
RL_{in}	input return loss	$P_L = 250\text{ W}$	-	-10	-	dB
η_D	drain efficiency	$P_L = 250\text{ W}$	<tdb>	72	-	%



7. Test information

7.1 Ruggedness in class-AB operation

The BLF182XR and BLF182XRS are capable of withstanding a load mismatch corresponding to $V_{SWR} > 65 : 1$ through all phases under the following conditions: $V_{DS} = 50\text{ V}; I_{Dq} = 100\text{ mA}; P_L = 250\text{ W}$ pulsed; $f = 108\text{ MHz}$.

7.2 Impedance information

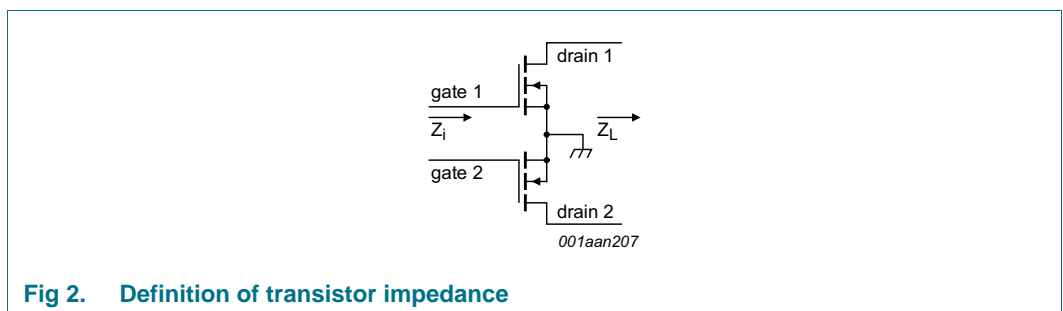


Table 9. Typical push-pull impedance

Simulated Z_i and Z_L device impedance; impedance info at $V_{DS} = 50\text{ V}$ and $P_L = 250\text{ W}$.

f (MHz)	Z_i (Ω)	Z_L (Ω)
108	<td>	<td>

7.3 UIS avalanche energy

Table 10. Typical avalanche data per section

$T_{amb} = 25\text{ °C}$; typical test data; test jig without water cooling.

I_{AS} (A)	E_{AS} (J)
<td>	<td>
<td>	<td>
<td>	<td>

For information see application note *AN10273*.

8. Package outline

Flanged LDMOST ceramic package; 2 mounting holes; 4 leads

SOT1121A

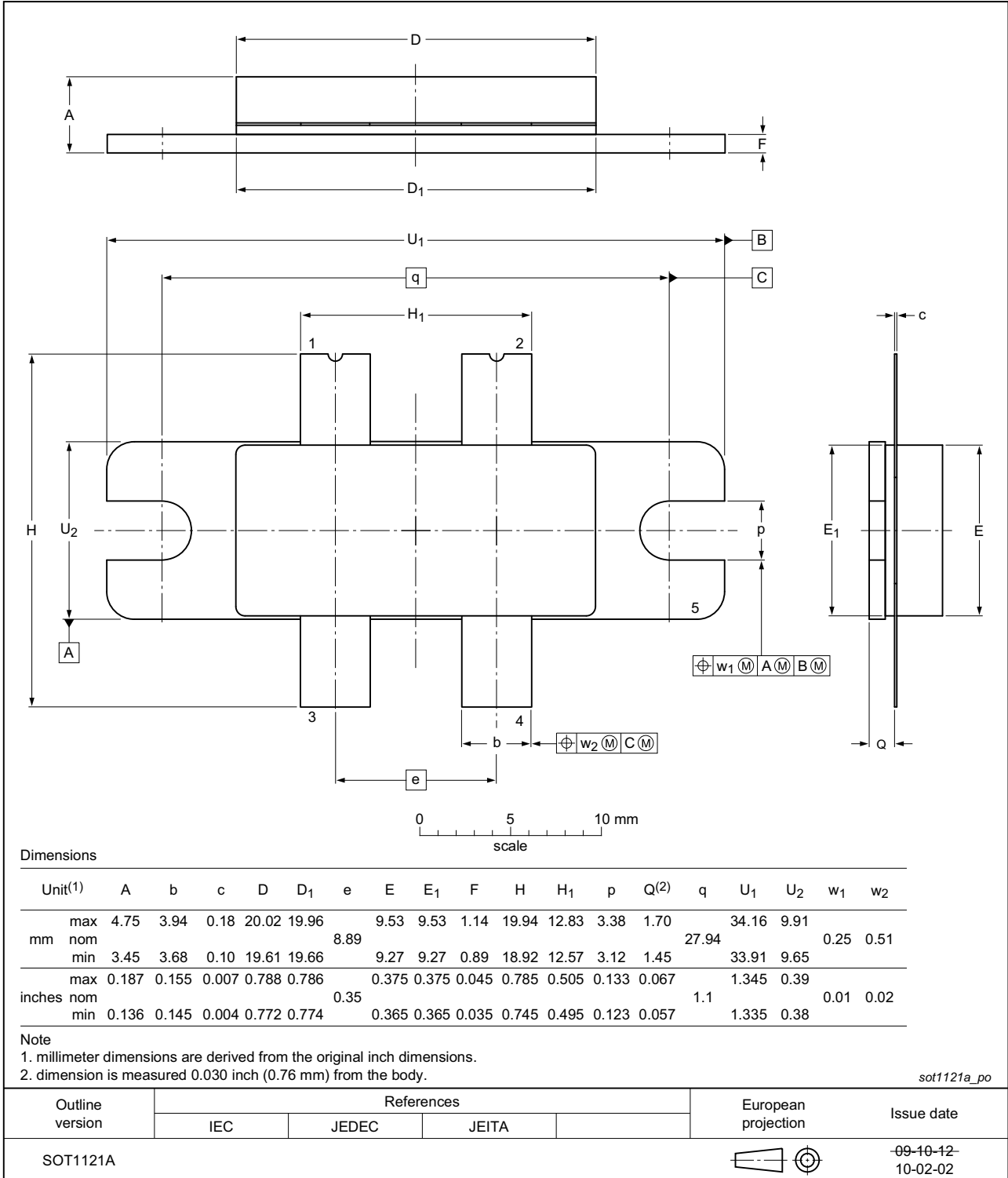


Fig 3. Package outline SOT1121A

Earless flanged ceramic package; 4 leads

SOT1121B

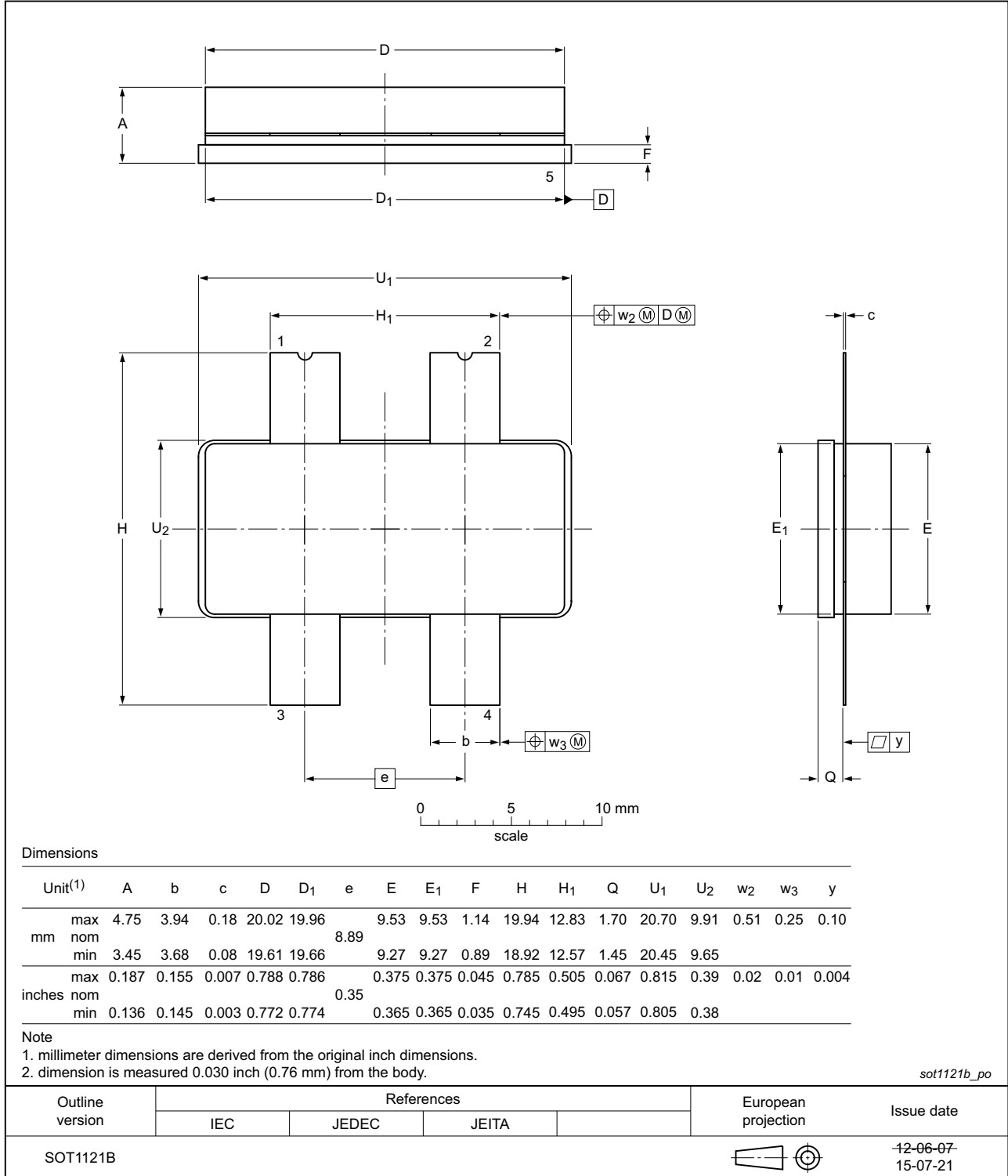


Fig 4. Package outline SOT1121B

9. Handling information

CAUTION



This device is sensitive to ElectroStatic Discharge (ESD). Observe precautions for handling electrostatic sensitive devices.

Such precautions are described in the *ANSI/ESD S20.20*, *IEC/ST 61340-5*, *JESD625-A* or equivalent standards.

10. Abbreviations

Table 11. Abbreviations

Acronym	Description
CW	Continuous Wave
ESD	ElectroStatic Discharge
HF	High Frequency
LDMOS	Laterally Diffused Metal-Oxide Semiconductor
LDMOST	Laterally Diffused Metal-Oxide Semiconductor Transistor
MTF	Median Time to Failure
SMD	Surface Mounted Device
UIS	Unclamped Inductive Switching
VSWR	Voltage Standing-Wave Ratio

11. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BLF182XR_BLF182XRS v.1	20150723	Objective data sheet	-	-

12. Legal information

12.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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14. Contents

1	Product profile	1
1.1	General description	1
1.2	Features and benefits	1
1.3	Applications	1
2	Pinning information	2
3	Ordering information	2
4	Limiting values	2
5	Thermal characteristics	3
6	Characteristics	3
7	Test information	4
7.1	Ruggedness in class-AB operation	4
7.2	Impedance information	4
7.3	UIS avalanche energy	5
8	Package outline	6
9	Handling information	8
10	Abbreviations	8
11	Revision history	8
12	Legal information	9
12.1	Data sheet status	9
12.2	Definitions	9
12.3	Disclaimers	9
12.4	Trademarks	10
13	Contact information	10
14	Contents	11

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